

What is claimed is:

1. A process for packaging an organic light-emitting panel, comprising:  
forming a patterned desiccant on a cover plate by ink-jet printing;  
crosslinking the patterned desiccant;  
5 providing an adhesive frame between a substrate having organic light-emitting diodes and the cover plate;  
compressing the cover plate and the substrate; and  
crosslinking the adhesive frame.
2. The process for packaging an organic light-emitting panel of claim 1, wherein  
10 the desiccant comprises thermally crosslinked desiccant.
3. The process for packaging an organic light-emitting panel of claim 2, wherein the step of crosslinking the desiccant is performed by a thermal process.
4. The process for packaging an organic light-emitting panel of claim 1, wherein the desiccant comprises a radiated crosslinked desiccant.
- 15 5. The process for packaging an organic light-emitting panel of claim 4, wherein the step of crosslinking the desiccant is performed by a radiation exposure process.
6. The process for packaging an organic light-emitting panel of claim 1, wherein the step of crosslinking the desiccant is performed in inert gas and/or under low pressure environment.
- 20 7. The process for packaging an organic light-emitting panel of claim 1, wherein the adhesive frame comprises thermally crosslinked frame .
8. The process for packaging an organic light-emitting panel of claim 7, wherein the step of crosslinking the adhesive frame is performed by a thermal process.

9. The process for packaging an organic light-emitting panel of claim 1, wherein the adhesive frame comprises a radiated crosslinked frame.

10. The process for packaging an organic light-emitting panel of claim 9, wherein the step of crosslinking the adhesive frame is performed by a radiation exposure process.

11. The process for packaging an organic light-emitting panel of claim 1, further comprising aligning the substrate having the organic light-emitting diodes to the cover plate with the patterned desiccant thereon prior to the step of compressing the cover plate and the substrate.

12. A method of forming desiccant, comprising:  
providing a substrate;  
ink-jetting a desiccant on the cover plate by ink-jet printing; and  
crosslinking the desiccant.

13. The method of forming desiccant of claim 12, wherein the desiccant comprises thermally crosslinked desiccant.

14. The method of forming desiccant of claim 13, the step of crosslinking the desiccant is performed by a thermal process.

15. The method of forming desiccant of claim 12, wherein the desiccant comprises a radiated crosslinked desiccant.

16. The method of forming desiccant of claim 15, wherein step of crosslinking the desiccant is performed by a radiation exposure process.

17. An organic light-emitting panel, comprising:  
a substrate, having organic light-emitting diodes;  
a cover plate, over the substrate;

a patterned desiccant, on the cover plate, facing to the substrate; and  
an adhesive frame, between the substrate and the cover plate.

18. The organic light-emitting panel of claim 17, wherein the patterned desiccant  
is continuous, discontinuous, solid, hollow, or the combination thereof.

5        19. A coating apparatus, comprising:  
  
an ink-jet printing device, for ink-jetting a desiccant on a cover plate;  
a crosslinking device, for crosslinking the desiccant; and  
a buffer chamber, connecting to the ink-jet printing device and the crosslinking  
device for transferring the cover plate.

10        20. The coating apparatus of claim 19, wherein the crosslinking device  
comprises an oven.

21. The coating apparatus of claim 19, wherein the crosslinking device  
comprises a radiation exposure equipment.

22. The coating apparatus of claim 19, further comprising a loading/unloading  
15        unit connected to the buffer chamber.

23. The coating apparatus of claim 19, wherein the ink-jet printing device  
comprises an ink-jet printing head.